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solder "theoretical density"

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**Circuit breaker contact containing silver and graphite fibers - group of 2 »**

SD Sinharoy, JL McKee, NS Hoyer - US Patent 4,699,763, 1987 - Google Patents  
... contactswwhich are baked, sintered, repressed, resintered, re-repressed, and **solder**  
flushed to ... to obtain a density at close 50 to **theoretical density** as possible ...  
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**SEMICONDUCTOR DEVICE WITH THERMALLY CONDUCTIVE DIELECTRIC BARRIER**

US Patent 3,609,471 - Google Patents  
... having a density greater than about 80 percent the **theoretical density** of aluminum ...  
with an extended surface portion thereof, metallic **solder** means providing an ...  
Cited by 15 - [Related Articles](#) - [Web Search](#)

**ELECTRONIC DEVICE WITH THERMALLY CONDUCTIVE DIELECTRIC BARRIER**

RI Scaze - US Patent 3,716,759, 1973 - Google Patents  
... **theoretical density**, but formed from a commercially 55 thin layer of nickel which  
is in turn followed by ... **solder** is then utilized capable of alloying with silver ...  
Cited by 15 - [Related Articles](#) - [Web Search](#)

**BERYLLIUM OXIDE MICROELECTRONIC PACKAGE**

PS Hessinger - US Patent 3,312,771, 1987 - Google Patents  
... 53 which is metallized to provide a fairly wide area for **soldering** the ceramic  
or metal cover 53 ... (as compared with the maximum **theoretical density** of 3.008 g ...  
Cited by 8 - [Related Articles](#) - [Web Search](#)

**High-density-infrared transient liquid coatings - group of 2 »**

C Blue - JOM(USA), 2000 - tms.org  
... Coating densities as high as 98-100 percent of **theoretical density** have been ... It is  
used for drying **solder** resists in the electronics industry, browning and ...  
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**BEST AVAILABLE OOFX**

H Schreiner - US Patent 3,913,201 - Google Patents  
... 1/cm 2, the sintered body attained a **theoretical density** ... as copper, brass, bronze,  
CuBe, etc., an impeccable wetting through the hard **solder** and, therefore ...  
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**METHOD OF SECURING DENSE, METAL-BONDED REFRACTORY NITRIDE BODIES TO STEEL**

AB Palmer - US Patent 3,549,337, 1970 - Google Patents  
... to the tool, for example, by using a low-melting silver **solder** and a ... said  
interdispersion having a density in excess of 98% of its **theoretical density** and ...  
Cited by 7 - [Related Articles](#) - [Web Search](#)

**Superficial coating layer having acicular structures for electrical conductors - group of 2 »**

A Parthasarathi, WL Brenneman - US Patent 5,573,845, 1996 - Google Patents  
... and the coating had a density of 100% of the **theoretical density** of that coating ...  
electrical assembly of claim 8 wherein said second portion is coated with **solder**. ...  
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solder "relative density"

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**Multi-layer ceramic wiring circuit board and process for producing the same - group of 2 »**

N Ushifusa, S Ogihara, K Nagayama - US Patent 4,620,264, 1986 - Google Patents  
... These inner-layer insulating sub- 40 strates 2 had a **relative density** of approximately 85 ... ceramic were joined to the surface conductor layers 7 by **solder** 9. The ...  
[Cited by 28](#) - [Related Articles](#) - [Web Search](#)

**Sputtering target for producing electroconductive transparent films and process for manufacture ...**

US Patent 5,160,675, 1992 - freepatentsonline.com  
... any bonding, there is no chance of possible melting of **soldering** materials and ...  
Furthermore, ITO targets with a **relative density** larger than 70% can be prepared ...  
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**Ceramic packaged semiconductor device - group of 4 »**

Y Matsushita, K Nakamura, M Ura - US Patent 4,517,584, 1985 - Google Patents  
... The resulting sintered SiC- based substrate having a **relative density** of 99% or more is ... First of all, an Au-Si eutectic **solder** is provided on 65 the desired ...  
[Cited by 23](#) - [Related Articles](#) - [Web Search](#)

**Development and characterisation of direct laser sintering Cu-based metal powder - group of 3 »**

HH Zhu, L Lu, JYH Fuh - Journal of Materials Processing Tech., 2003 - Elsevier  
... using various metal systems such as Cu-Sn, bronze-Ni, Cu-**solder** and Cu ... parts produced by direct laser sintering are usually with 60-70% **relative density**. ...  
[Cited by 17](#) - [Related Articles](#) - [Web Search](#)

**Electrically insulating substrate and a method of making such a substrate - group of 2 »**

Y Matsushita, Y Takeda, K Nakamura, T Okoshi - US Patent 4,370,421, 1983 - Google Patents  
... directly brazed to the silicon element 11 via the **solder** 19 ... TABLE 8 **Relative density** (%)  
Thermal conductivity (cal/cm • sec Electrical resistivity (Ohm • cm ...  
[Cited by 12](#) - [Related Articles](#) - [Web Search](#)

**Sintered aluminum nitride and semi-conductor device using the same - group of 2 »**

Y Takeda, S Ogihara, M Ura, K Nakamura, T Asai, T ... - US Patent 4,540,673, 1985 - Google Patents  
... The compact sintered products having a **relative density** of 90% or higher had a ... 4,540,673  
10 the **solder** 19, with or without metallizing the contact surface of ...  
[Cited by 31](#) - [Related Articles](#) - [Web Search](#)

**Method, system and composition for soldering by induction heating - group of 2 »**

TH McGaffigan - US Patent 5,093,545, 1992 - Google Patents  
... Another consideration in the selection of particles is 65 the **relative density** of the particles compared to the density of the **solder**. ...